

Title (en)

DEVICE AND METHOD FOR PROCESSING MATERIAL BY MEANS OF LASER RADIATION

Title (de)

VORRICHTUNG UND VERFAHREN ZUR MATERIALBEARBEITUNG MITTELS LASERSTRAHLUNG

Title (fr)

DISPOSITIF ET PROCÉDÉ POUR LE TRAITEMENT DE MATIÈRE AU MOYEN D'UN RAYONNEMENT LASER

Publication

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Application

EP 20746134 A 20200720

Priority

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Abstract (en)

[origin: CA3148493A1] The invention relates to a method for processing material, in particular for modifying material and/or material properties, by means of laser radiation, comprising the following steps: a) generating a multiplicity of laser pulses (L); b) controlling the point of impact of the laser pulses (L) on a workpiece (100) to be processed, in particular deflecting the laser pulses (L) and/or moving the workpiece (100) to be processed, such that the laser pulses (L) are guided along a predetermined trajectory (Z) on the workpiece (100) to be processed. According to the invention, - a pulse-to-pulse time interval (?t) between the individual laser pulses (L) generated and/or - a pulse energy (Pi) of the laser pulses (L) and/or - a beam diameter (D) of the laser pulses (D) and/or - the predetermined trajectory (Z) is/are specifically subjected to noise.

IPC 8 full level

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CPC (source: EP US)

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